

Abstract

A polishing body, e.g., pad (200, 230, 260, 300) or belt (400, 500) having a polishing layer (214, 404) that includes a backmixing region (202, 232, 262, 308, 416, 508) wherein backmixing can occur within a slurry (116) between a wafer (204, 234, 264, 304, 408), or other article, and the polishing layer under certain conditions. The polishing layer includes a first groove configuration (206, 236, 266, 312, 428, 504) within the backmixing region and a second groove configuration (208, 238, 268, 320, 432, 520) outside of the backmixing region that is different from the first groove configuration. The first groove configuration is designed based upon whether or not the presence of spent slurry within the backmixing region is detrimental or beneficial to polishing the wafer.